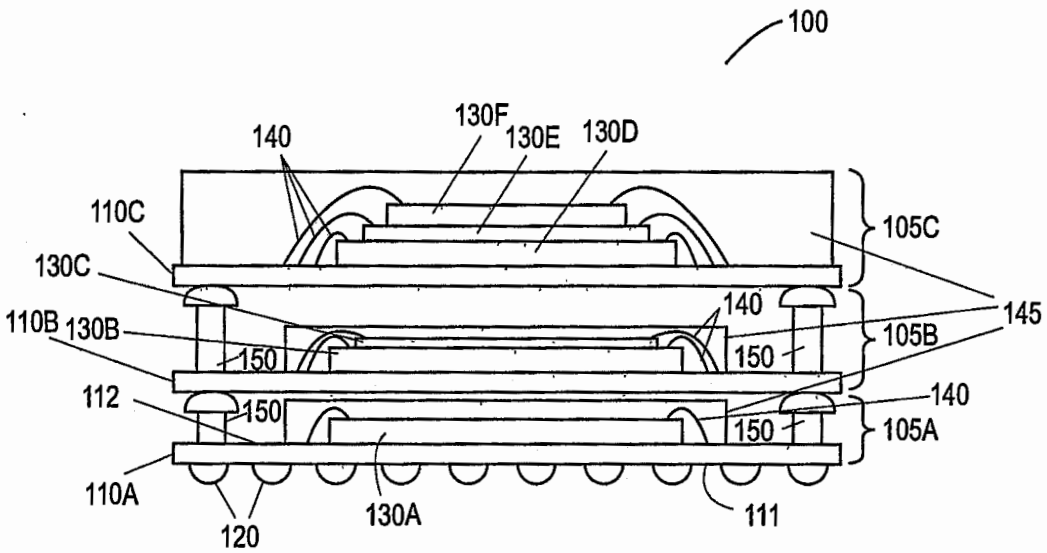


FIG. 1
(PRIOR ART)

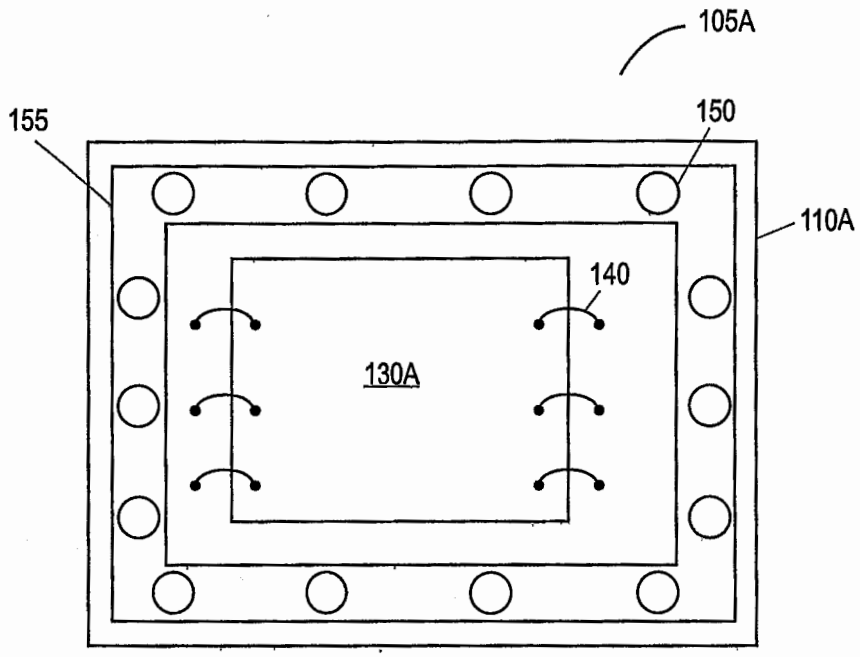


FIG. 1A
(PRIOR ART)

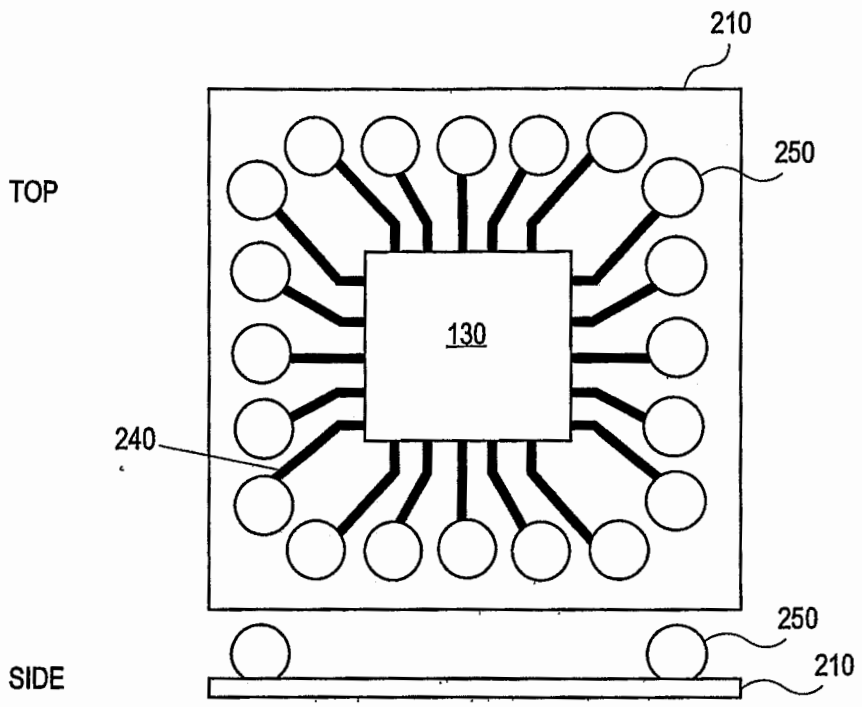


FIG. 2

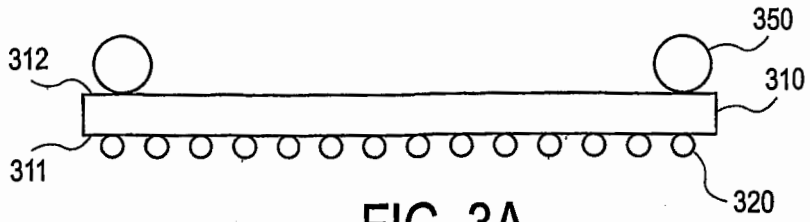


FIG. 3A

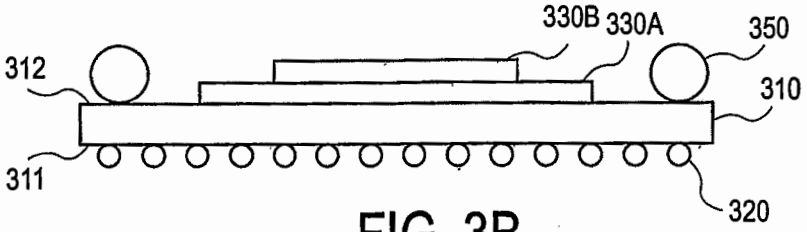


FIG. 3B

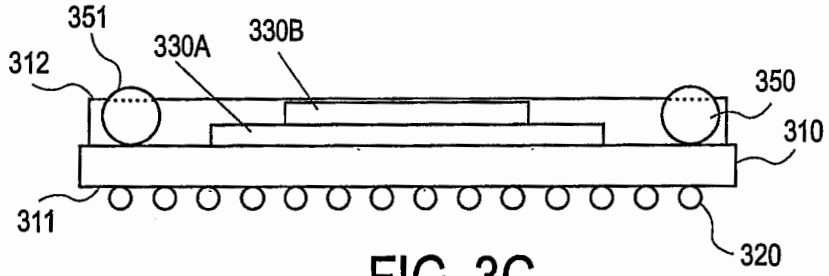


FIG. 3C

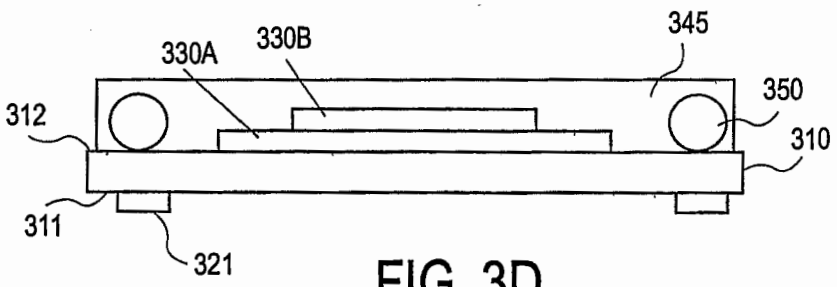


FIG. 3D

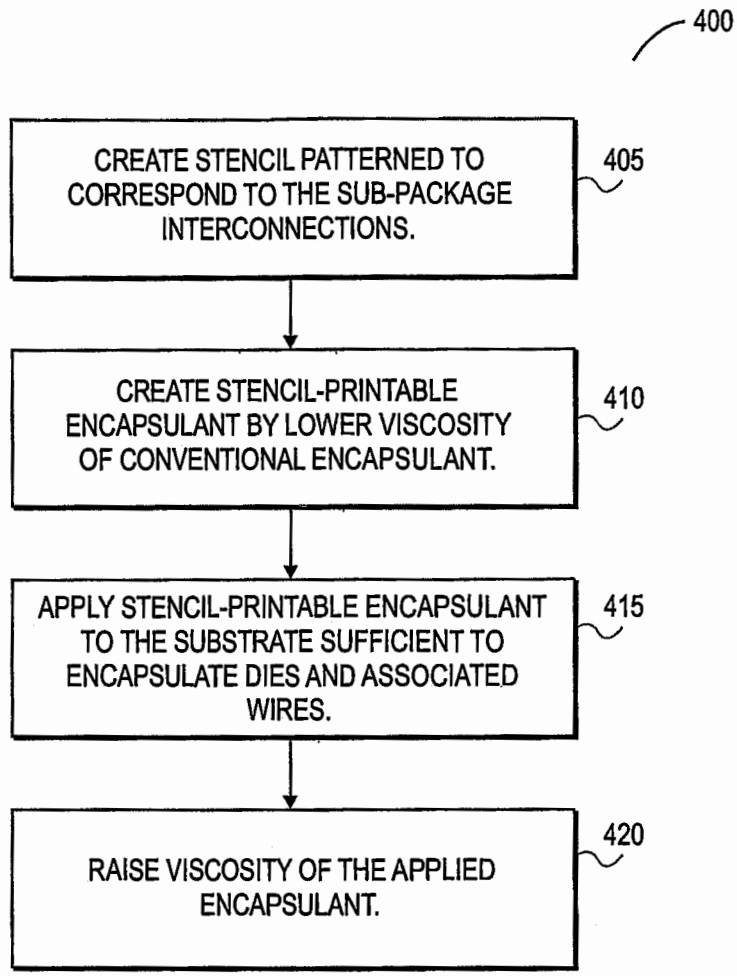

400
CREATE STENCIL PATTERNED TO CORRESPOND TO THE SUB-PACKAGE INTERCONNECTIONS.
405
CREATE STENCIL-PRINTABLE ENCAPSULANT BY LOWER VISCOSITY OF CONVENTIONAL ENCAPSULANT.
410
APPLY STENCIL-PRINTABLE ENCAPSULANT TO THE SUBSTRATE SUFFICIENT TO ENCAPSULATE DIES AND ASSOCIATED WIRES.
415
RAISE VISCOSITY OF THE APPLIED ENCAPSULANT.
420

FIG. 4

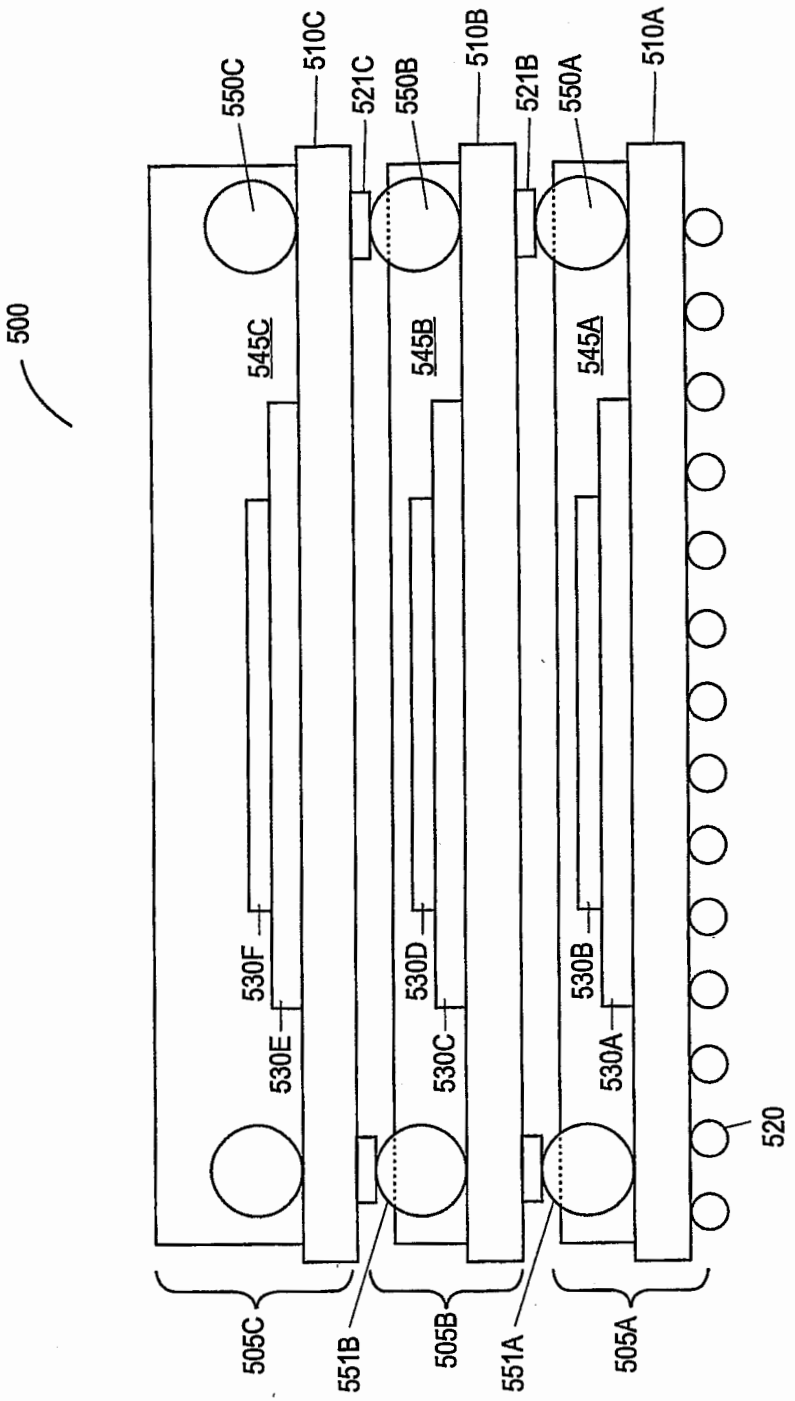

500
550C
510C
521C
550B
510B
521B
550A
510A
545C
545B
545A
530F
530E
530D
530C
530B
530A
520
505C
551B
505B
551A
505A

FIG. 5